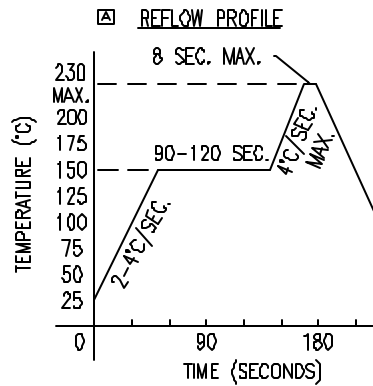
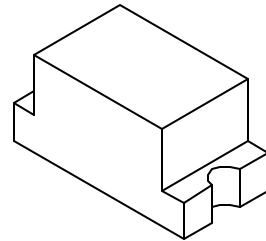
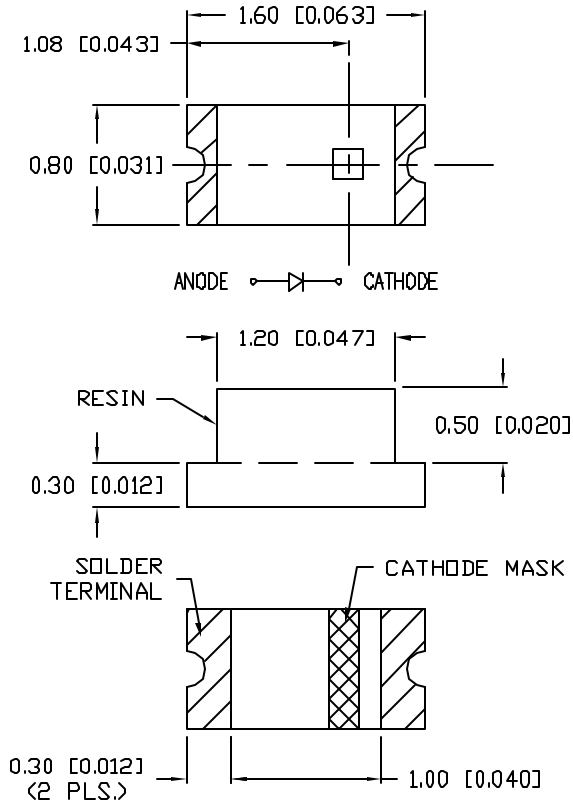
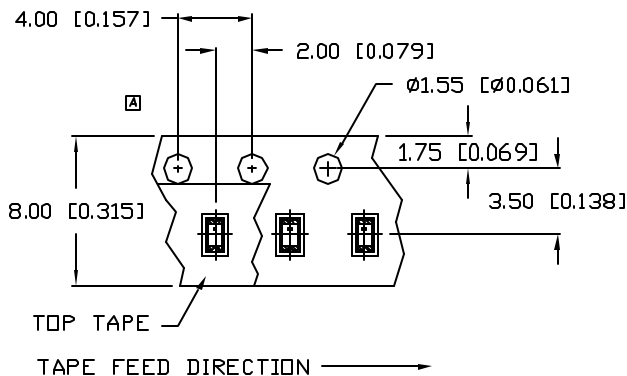
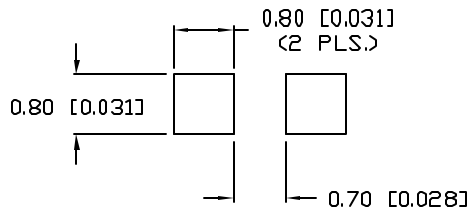


UNCONTROLLED DOCUMENT



RECOMMENDED SOLDER PAD LAYOUT



\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030), MIN.= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

PART NUMBER  
SML-LX0603SGW-TR

REV.  
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10644.	7.18.00

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		567		nm	
FORWARD VOLTAGE		2.2	2.6	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY		20		med	$I_f=20\text{mA}$
VIEWING ANGLE		160		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	50	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-25 TO +85	°C
STORAGE TEMP.	-30 TO +85	°C

\*  $t < 10\mu\text{s}$

NOTES:

- 4,000 PIECES PER REEL.
- THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE

- SHELF LIFE IN SEALED BAG: 12 MONTHS AT <40°C AND <90% RELATIVE HUMIDITY (RH).
- AFTER THIS BAG IS OPENED, DEVICES HAVE TO BE MOUNTED WITHIN 48 HOURS OR STORED AT <30% RH.

UNCONTROLLED DOCUMENT

REV. A PART NUMBER SML-LX0603SGW-TR

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290 E. HELLEN ROAD  
PALATINE, ILLINOIS 60067  
PHONE: (847) 359-2790  
WEB: <http://www.lumex.com>

1.6mm x 0.8mm PCB CHIP, SURFACE MOUNT LED,  
567nm SUPER GREEN LED, MILKY WHITE DIFFUSED LENS.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 6.14.99
			PAGE: 1 OF 1
			SCALE: N/A